



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **50**

Number of Rows: **2**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	50
Number of Rows	2
Board-to-Board Configuration	Parallel

Electrical Characteristics

Dielectric Withstanding Voltage (Max)	500 VAC
Insulation Resistance	5000 MΩ



Operating Voltage	30 VAC
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Body Features

Connector Profile	Standard
Primary Product Color	Black

Contact Features

Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 - 6.35 µm[150 - 250 µin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 µm[30 µin]
Contact Type	Pin
Contact Current Rating (Max)	3.6 A

Termination Features

Round Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

Mechanical Attachment

Mating Retention	With
Mating Retention Type	Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP

Dimensions

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Row-to-Row Spacing	2.54 mm[.1 in]
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PCB Thickness (Recommended)	1.57 mm[.062 in]
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Usage Conditions

Housing Temperature Rating	High
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Operating Temperature Range	-65 - 105 °C[-85 - 221 °F]
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Operation/Application

Solder Process Feature	Board Standoff
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Circuit Application	Signal
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Industry Standards

UL Rating	Recognized
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Compatible With Agency/Standards Products	CSA, UL
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Compatible With Approved Standards Products	CSA LR7189, UL E28476
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UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	13
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Packaging Method	Box, Tube
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Other

Position Locations Omitted	0
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Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Wave solder capable to 260°C
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Product Compliance Disclaimer



This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

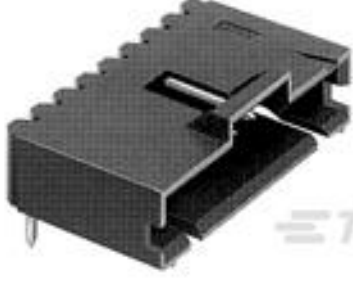
Also in the Series | AMPMODU System 50

PCB Headers & Receptacles(1008)

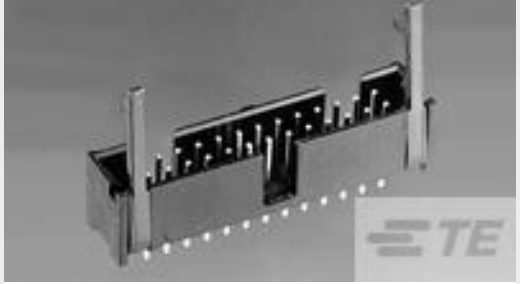
Customers Also Bought



TE Part # 5-103414-3
05 MODII HDR SRST SHRD LF



TE Part # 5-103635-7
08 MTE HDR SRRA LTCH.100CL LF



TE Part # 2-1761609-3
IDC LOW PRO HDR 10P RA SHT LAT



TE Part # 5-103168-7
18 MODII HDR DRST SHRD .100CL



TE Part # 650945-5
064 EURO TYPE C PIN ST ASSY



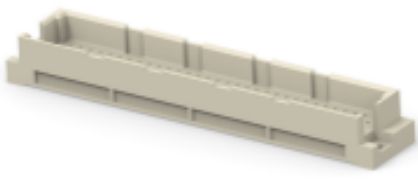
TE Part # 2560-220-2031
CONT PIN



TE Part # 3-87977-4
18 MODIV HSG COMP DR .100 POL



TE Part # 2-1618382-5
JPS10-1Y = M28750/10-001Y



TE Part # 434555-E
FRAEZT 11,6 TE * 172 * J 1 434555
FUEHRU

Documents

Product Drawings

50 SYSTEM 50 HDR DRST SHRD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-104068-5_S.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-104068-5_S.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-104068-5_S.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages



AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Ribbon Cable Interconnect Solutions

English

Product Specifications

Application Specification

English